

APPENDIX

Changes to Claims:

The following is a marked-up version of the amended claim:

8. (Amended) A semiconductor device, comprising:

a semiconductor chip having electrodes; a substrate having an interconnect pattern; and an adhesive;

wherein said electrodes and said interconnect pattern are electrically connected; and

wherein said adhesive ~~is~~ has a first portion interposed between ~~a~~-surface of said substrate on which said interconnect pattern is formed and ~~a~~-surface of said semiconductor chip on which said electrodes are formed, and a second portion formed next to said first portion and on ~~so as to cover~~ at least a part of ~~a~~-lateral surface of said semiconductor chip at least a part of said second portion having a thickness greater than said first portion.

Claims 16-20 are added.